



**ZXMP2120G4** 

### **Product Summary**

V <sub>(BR)</sub> dss	Rds(on)	I <sub>D</sub> T <sub>A</sub> = +25°C
-200V	25Ω @ V <sub>GS</sub> = 10V	200mA

### Description

This new generation trench MOSFET features a unique structure combining the benefits of low on-resistance and fast switching, making it ideal for high efficiency power management applications.

### **Applications**

Active clamping of primary aide MOSFETs in 48 Volt DC-DC converters

### **Features and Benefits**

- High Voltage
- Low On-resistance
- Fast Switching Speed
- Low Gate Drive
- Low Threshold
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

200V P-CHANNEL ENHANCEMENT MODE MOSFET

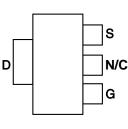
Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

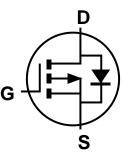
- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish (3)
- Weight: 0.112 grams (Approximate)



Top View



Pin Out - Top



Equivalent Circuit

### Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMP2120G4TA	ZXMP2120	7	12	1,000
ZXMP2120G4TC	ZXMP2120	13	12	4,000

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

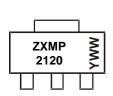
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

Notes:



SOT223

 $\begin{array}{l} \mbox{ZXMP2120} = \mbox{Product Type Marking Code} \\ \mbox{YWW} = \mbox{Date Code Marking} \\ \mbox{Y or } \overline{Y} = \mbox{Last Digit of Year (ex: 5 = 2015)} \\ \mbox{WW or } \overline{WW} = \mbox{Week Code (01~53)} \end{array}$ 



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-200	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current ( $V_{GS} = 10V$ ; $T_A = +25^{\circ}C$ ) (Note 5)	ID	-200	mA
Pulsed Drain Current (Note 6)	I <sub>DM</sub>	-1	A
Pulsed Source Current (Body Diode) (Note 6)	I <sub>SM</sub>	-1	A

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation at $T_A = +25^{\circ}C$ (Note 5) Linear Derating Factor	PD	2.0 1.6	₩ mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	62.5	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-200	-	-	V	$V_{GS} = 0V, I_D = -1mA$	
Zero Gate Voltage Drain Current	IDSS	-	-	-10 -100	μA	V <sub>DS</sub> = -200V, V <sub>GS</sub> = 0V V <sub>DS</sub> = -160V, V <sub>GS</sub> = 0V, T = +125°C	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	20	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1.5	-	-3.5	V	$V_{DS} = V_{GS}, I_D = -1mA$	
Static Drain-Source On-Resistance (Note 7)	R <sub>DS(ON)</sub>	-	-	25	Ω	$V_{GS} = -10V, I_D = -150mA$	
Forward Transconductance (Notes 7 & 8)	<b>g</b> fs	50	-	-	mS	$V_{DS} = -25V, I_D = -150mA$	
On-State Drain Current (Note 7)	I <sub>D(ON)</sub>	-300	-	-	mA	V <sub>DS</sub> = -25V, V <sub>GS</sub> = -10V	
DYNAMIC CHARACTERISTICS							
Input Capacitance (Note 8)	C <sub>iss</sub>	-	-	100	pF		
Output Capacitance (Note 8)	C <sub>oss</sub>	-	-	25	pF	V <sub>DS</sub> = -25V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Reverse Transfer Capacitance (Note 8)	Crss	-	-	7	pF	1 = 1.000	
Turn-On Delay Time (Notes 8 & 9)	t <sub>D(ON)</sub>	-	-	7	ns		
Turn-On Rise Time (Notes 8 & 9)	t <sub>R</sub>	-	-	15	ns		
Turn-Off Delay Time (Notes 8 & 9)	t <sub>D(OFF)</sub>	-	-	12	ns	V <sub>DD</sub> = -25V, I <sub>D</sub> = -150mA	
Turn-Off Fall Time (Notes 8 & 9)	t <sub>F</sub>	-	-	15	ns		

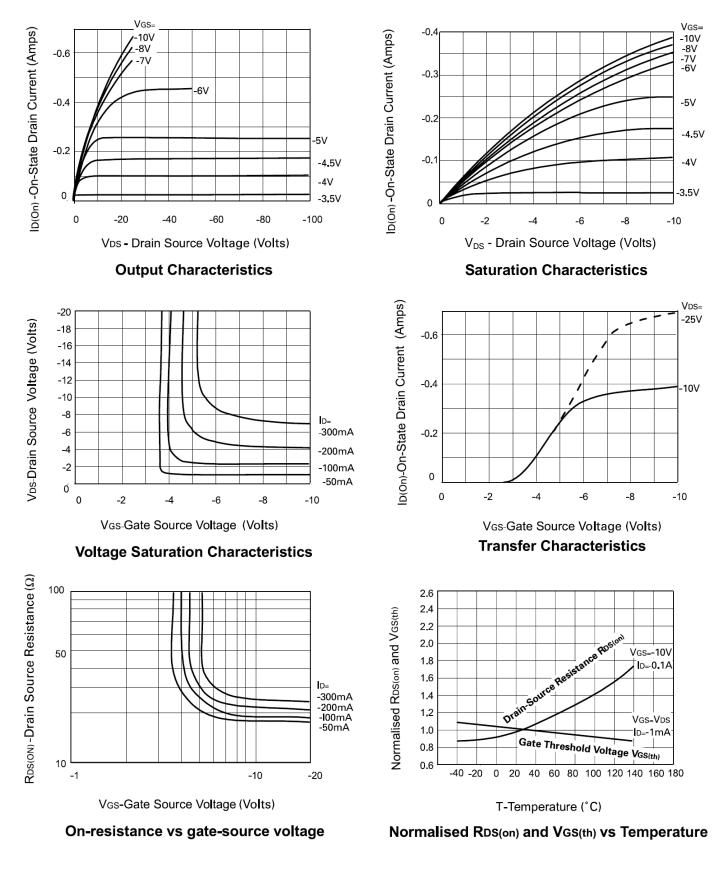
 For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph. Notes:

7. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%. 8. Sample test.

9. Switching characteristics are independent of operating junction temperature.

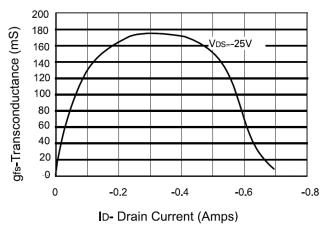


# ZXMP2120G4

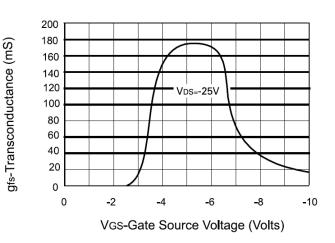


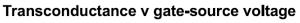


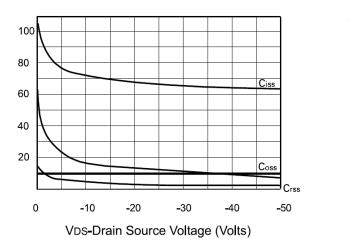
C-Capacitance (pF)



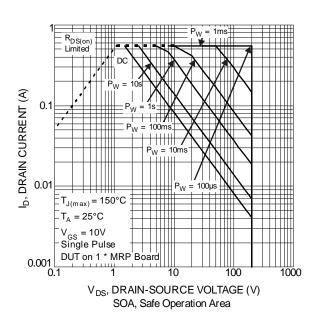
Transconductance v drain current

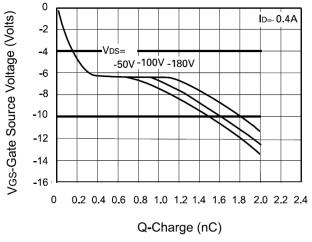






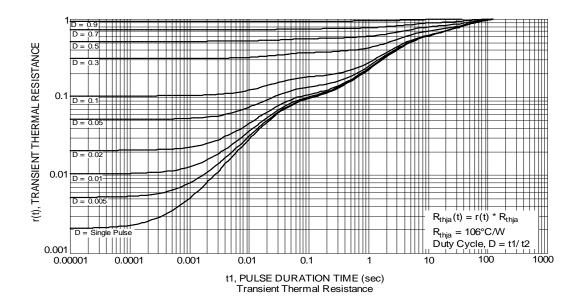
Capacitance v drain-source voltage





Gate charge v gate-source voltage

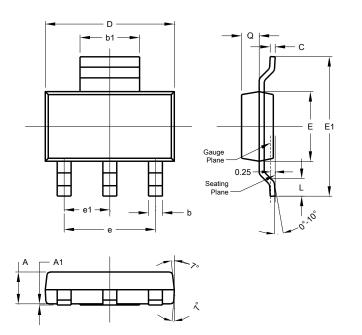






# **Package Outline Dimensions**

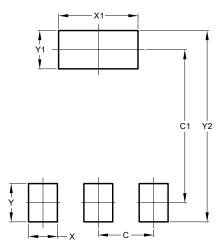
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT223				
Dim	Min	Max	Тур	
Α	1.55	1.65	1.60	
A1	0.010	0.15	0.05	
b	0.60	0.80	0.70	
b1	2.90	3.10	3.00	
С	0.20	0.30	0.25	
D	6.45	6.55	6.50	
Е	3.45	3.55	3.50	
E1	6.90	7.10	7.00	
е	-	-	4.60	
e1	-	-	2.30	
L	0.85	1.05	0.95	
Q	0.84	0.94	0.89	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00



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